

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



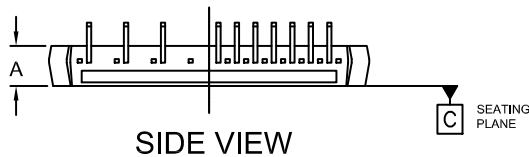
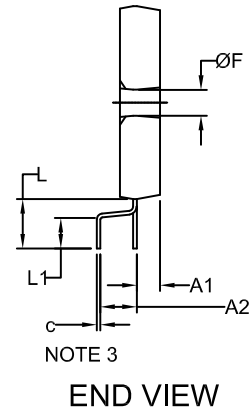
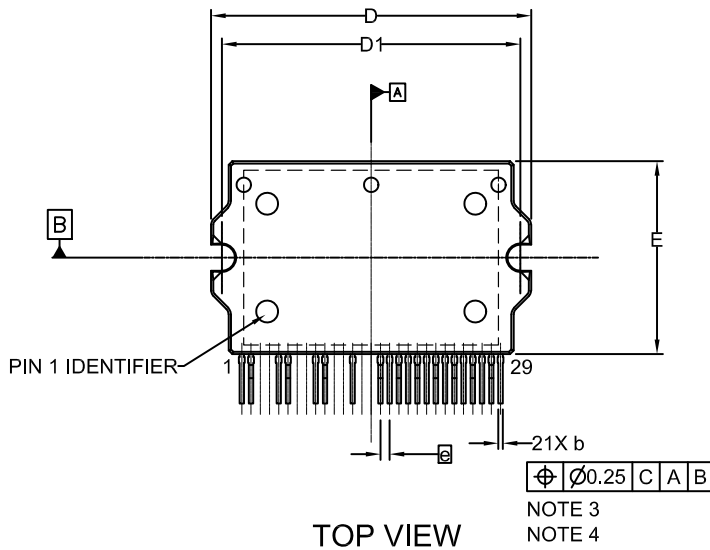
SIP29 44x26.5
CASE 127ET
ISSUE O

DATE 18 AUG 2017

NOTES:

1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b and c APPLY TO THE PLATED LEADS AND ARE MEASURED BETWEEN 1.00 AND 2.00 FROM THE LEAD TIP.
4. POSITION OF THE LEAD IS DETERMINED AT THE ROOT OF THE LEAD WHERE IT EXITS THE PACKAGE BODY.
5. PIN 1 IDENTIFICATION IS A MIRRORED SURFACE INDENT.
6. MISSING PINS ARE 3,4,7,8,11,12,14 AND 15.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	5.00	5.50	6.00
A1	2.70	3.20	3.70
A2	4.50	5.00	5.50
b	0.55	0.60	0.65
c	0.45	0.50	0.55
D	43.50	44.00	44.50
D1	40.50	41.00	41.50
E	26.00	26.50	27.00
e	1.27 BSC		
F	3.10	3.60	4.10
L	6.30	6.80	7.30
L1	3.80	4.30	4.80



DOCUMENT NUMBER:	98AON73701G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SIP29 44X26.5	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.